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Part Number: [0736422000](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits

Documents:

3D Model	Product Specification PS-73670-9999 (PDF)
Test Summary (PDF)	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

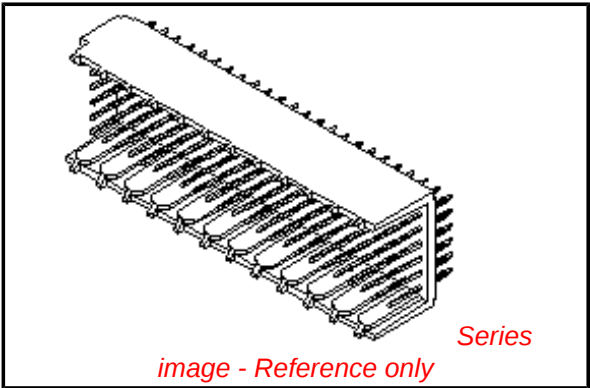
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	15



EU RoHS

RoHS Compliant by Exemption

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

China RoHS



Search Parts in this Series

[73642Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Flat Rock Tooling for Pneumatic Press	0622013700
HDM® Backplane Insertion Signal Contact Tool	0621001400
Extraction Tool	0621001000

Plating min: Termination (μm)	0.375
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SDA-73642-****

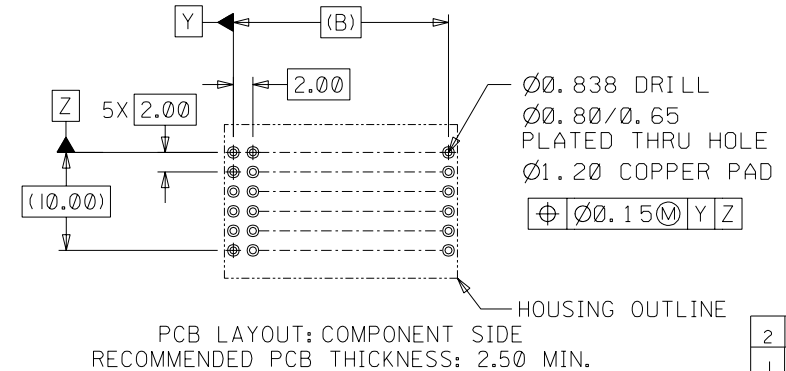
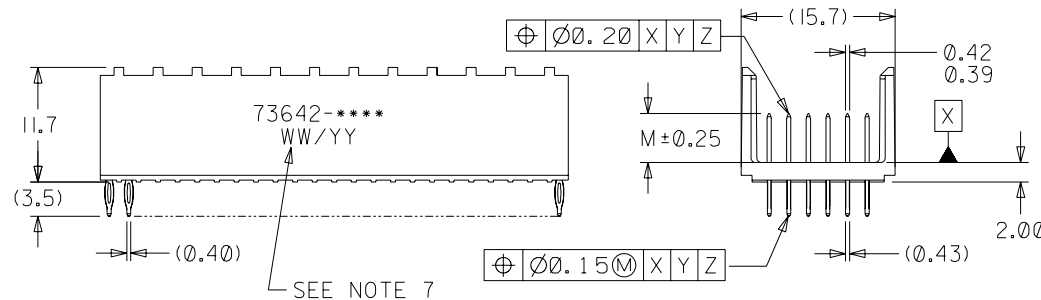
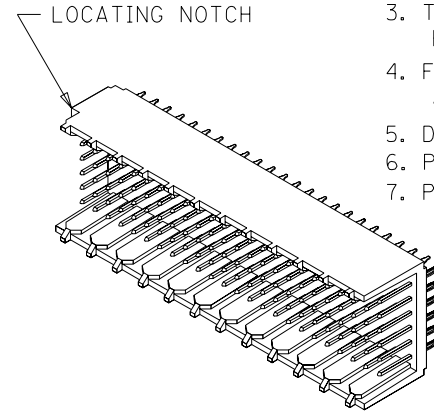
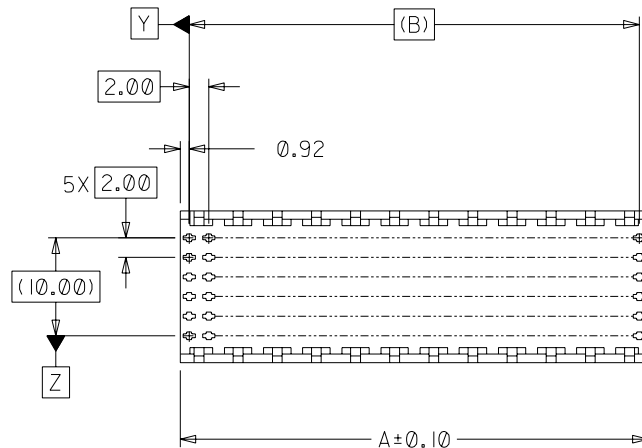
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

2	C
I	I
SH	REV

I	REVISED ECR UCP2003-2260 THOMAS 03/04/25	F	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	C	REVISED PER ECR *U81357 BINGHAM 97/12/15
H	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	E	REVISED ECR UDT1999-0243 BINGHAM 98/09/29	B	REVISED PER ECR *U70950 BINGHAM 97/02/14
G	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	D	REVISED ECR UDT1998-0240 BINGHAM 98/05/06	A	RELEASED FOR PROD. PER ECR *U70371 BINGHAM 96/12/18
LTR.	REVISIONS	LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	± N/A
2 PLACE	± N/A
1 PLACE	± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
DRWG. BY	JRR
CHK'D. BY	SMR
APP'D. BY	CAB
SCALE	2 : 1

 = 0		 = 0		REVISE ONLY ON CAD SYSTEM	
TITLE					
SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION					
 MOLEX INCORPORATED		SHEET NO.		DATE	
LITSE,ILL. 60532 U.S.A.		1 OF 2		96/12/18	
PART NO.		DRWG. NO.			
SEE SHEET 2		SDA-73642-****			
FILE NAME S73642X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DIV.
					SIZE

	10	9	8	7	6	5	4	3	2	1	73642
F											
E											
D											
C											
B											
A											

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-0000	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.00
73642-0100	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.50
73642-0200	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	6.00
73642-1000	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.00
73642-1100	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.50
73642-1200	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	6.00
73642-2000	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.00
73642-2100	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.50
73642-2200	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	6.00
73642-3000	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.00
73642-3100	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.50
73642-3200	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	6.00

		C	SEE SHEET I
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH			
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°			
INCH		METRIC	
3 PLACE	± N/A	---	
2 PLACE	± N/A	± 0.05	
1 PLACE	---	± 0.10	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	NO*NE

▽ = 0		▽ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE					
SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION					
molex		MOLEX INCORPORATED		SHEET NO.	DATE
LISLE,ILL.		60532 U.S.A.		2	97/12/15
PART NO.		DRWG. NO.			
SEE CHART		SDA-73642-*****			
FILE NAME		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO			DIV.
S73642X2		MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DA
DGN					B

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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